Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L1	56	(("4954412") or ("6203963") or ("6203961") or ("6203961") or ("6210853") or ("6299941") or ("6254929") or ("6541175") or ("6849371") or ("6830860") or ("6780560") or ("7029817") or ("5153089") or ("5153089") or ("5223370") or ("5290654") or ("5278020") or ("5308734") or ("5346790") or ("5346790") or ("5648193") or ("5660965") or ("5648193") or ("5645968") or ("5962177") or ("5698223") or ("5916725") or ("5916725") or ("5945245") or ("6063827") or ("6063827") or ("6110636") or ("5514513") or ("6020101") or ("6830860") or ("4877706") or ("5164282") or ("514824") or ("5164282") or ("514824") or ("5264314") or ("5500324") or ("5414052") or ("5484681") or ("5414052") or ("5484681") or ("5500324") or ("7041425") or ("6898851") or ("7041425") or ("5858601") or ("7320851") or ("7217444") or ("5320851") or ("7217444") or ("6013404")).PN.	USPAT	OR	OFF	2008/01/03 20:50

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L2	55	1 and (process method)[clm]	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 20:50
L3	25	2 and (emulsion aggregation)[clm]	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:23
L4	6599	((427/180) or (427/189) or (427/194) or (427/195) or (427/375) or (427/386)). CCLS.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	OFF	2008/01/03 21:24
L5	57	4 and (powder near3 toner)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:41
L6	20	5 and ((conductive metal\$3) near3 (substrate surface))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:41

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L7	13	6 and (epoxy epoxide)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:41
L8	13	7 and (heat\$3 melt\$3 fuse fused fusing fusion)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:41
L9	2	8 and (curing adj agent)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:41
L10	1334	4 and (powder near3 coat\$3)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:41
L11	642	10 and ((conductive metal\$3) near3 (substrate surface))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	ОR	ON	2008/01/03 21:41

L12	608	11 and (heat\$3 melt\$3 fuse fused fusing fusion)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:41
L13	384	12 and (epoxy epoxide)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T;	OR	ON	2008/01/03 21:41
		40 - 47 - 19 - 19	IBM_TDB	0-		
L14	145	13 and (curing adj agent)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:42
L15	35	14 and (resin near3 particle)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:57
L16	1	(emulsion with aggregat\$3 with coalesc\$3) same ((epoxy epoxide) near3 resin)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:58

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L17	231	(emulsion with aggregat\$3 with coalesc\$3) same resin	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 21:58
L18	10	(emulsion with aggregat\$3 with coalesc\$3) same resin same powder	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 22:01
L19	1	(emulsion with aggregat\$3 with coalesc\$3) same (epoxy epoxide)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 22:01
L20	5	(aggregat\$3 with coalesc\$3) same (epoxy epoxide)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 22:03
L21	1	(dispersi\$3 with aggregat\$3 with coalesc\$3) same (epoxy epoxide)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 22:08

L22	31	(("3800588") or ("6547869") or ("5300595") or ("5153239") or ("6491973") or ("6599992") or ("6140430") or ("6566433") or ("6635721") or ("6143457") or ("6582873") or ("6280798") or ("6680082") or ("6458501") or ("6197883") or ("5593807") or ("4079014") or ("3944493") or ("3590000") or ("4560635") or ("4007293") or ("3720617") or ("6218483") or ("5853943") or ("4394430") or ("3983045") or ("3655374") or ("5928830") or ("3864322")).PN.	USPAT	OR	OFF	2008/01/03 22:13
L23	3	(("5853943") or ("5593807") or ("5945245")).PN.	USPAT	OR	OFF	2008/01/03 22:14
L24	0	23 and (epoxy epoxide)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/03 22:14